

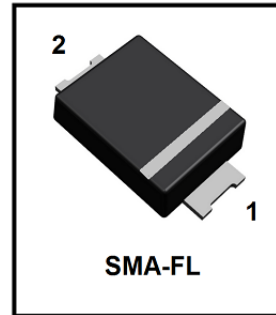
S-FFMAF201 thru S-FFMAF207T

Surface Mount Glass Passivated Junction Fast Recovery Rectifiers

Reverse Voltage 50 to 1000V Forward Current 2.0A

FEATURES

- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- * High temperature metallurgically bonded construction
- * Cavity-free glass passivated junction
- * Capable of meeting environmental standards of MIL-S-19500
- * Typical IR less than 1.0 μ A
- * High temperature soldering guaranteed: 260°C/10 seconds
- * S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- * We declare that the material of product compliance with RoHS requirements and Halogen Free.



Mechanical Data

Case: JEDEC SMA-FL, molded plastic over glass DIE

Terminals: Plated leads, solderable per

MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position Any

Weight: 28mg

Handling precaution: None

Electrical Characteristic

1. Maximum & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	S-FFMAF201	S-FFMAF202	S-FFMAF203	S-FFMAF204	S-FFMAF205	S-FFMAF206	S-FFMAF207	S-FFMAF207P	S-FFMAF207T	Unit	
Device marking code		FF21	FF22	FF23	FF24	FF25	FF26	FF27	FF27P	FF27T		
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	1000	1000	V	
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	700	700	V	
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	1000	1000	V	
Maximum average forward rectified current lead length at $T_C = 75^\circ\text{C}$ (Note 2)	$I_{F(AV)}$	2.0									A	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	60									A	
Typical reverse recovery time (Note 1)	t_{rr}	150			250	500	250	160			ns	
Typical thermal resistance (Note 2)	$R_{\theta JA}$ $R_{\theta JL}$	150					35					$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55 to +150									$^\circ\text{C}$	
storage temperature range	T_{STG}	-55 to +150									$^\circ\text{C}$	

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	S-FFMAF201	S-FFMAF202	S-FFMAF203	S-FFMAF204	S-FFMAF205	S-FFMAF206	S-FFMAF207	S-FFMAF207P	S-FFMAF207T	Unit	
Maximum instantaneous forward voltage at 2.0A	V_F	1.3									V	
Maximum DC reverse current $T_J = 25^\circ\text{C}$ at rated DC blocking voltage $T_J = 125^\circ\text{C}$	I_R	5.0					100					μA
Typical junction capacitance at 4.0V, 1MHz (Note 2)	C_J	15.0									PF	

NOTES:

1. $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $IRR = 0.25\text{A}$

2. 8.0mm^2 (.013mm thick) land areas

S-FFMAF201 thru S-FFMAF207T

2. Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

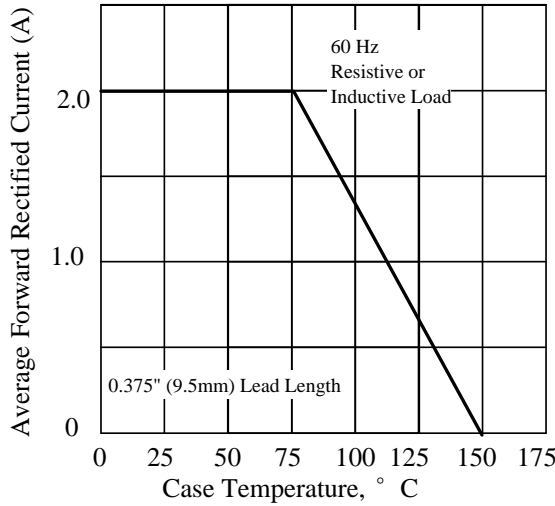


Fig. 2 - Maximum Non-repetitive Peak Forward Surge Current

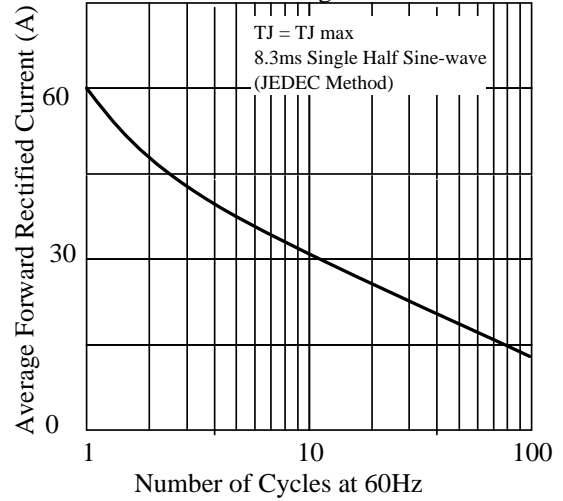


Fig 3. - Typical Instantaneous Forward Characteristics

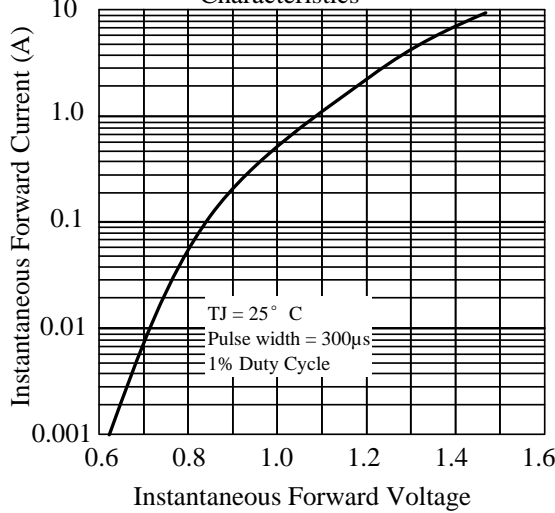


Fig 4. - Typical Reverse Characteristics

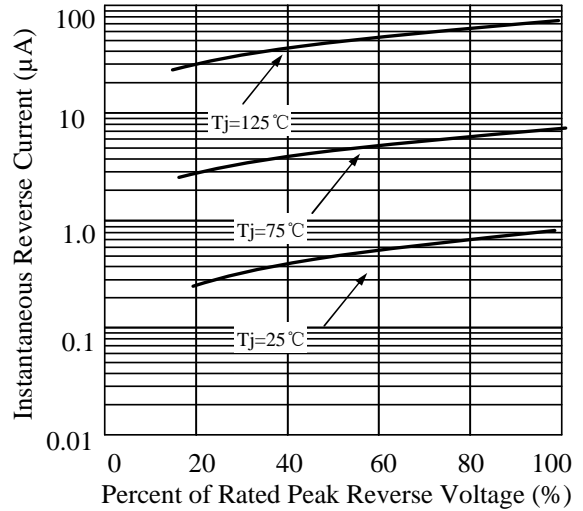


Fig 5. - typical transient thermal impedance

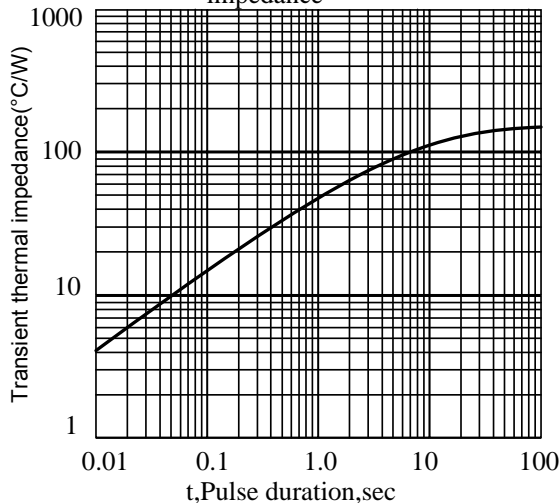
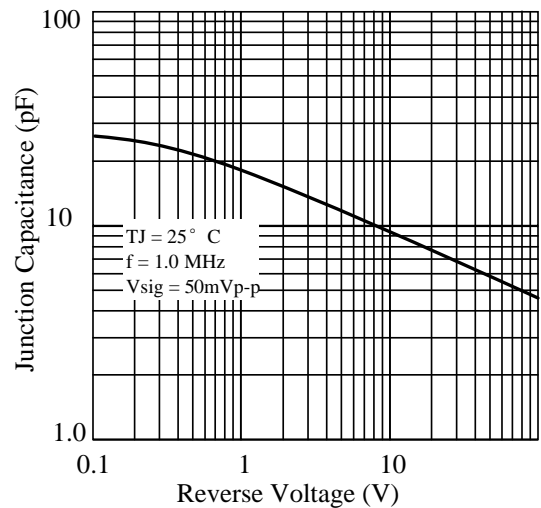
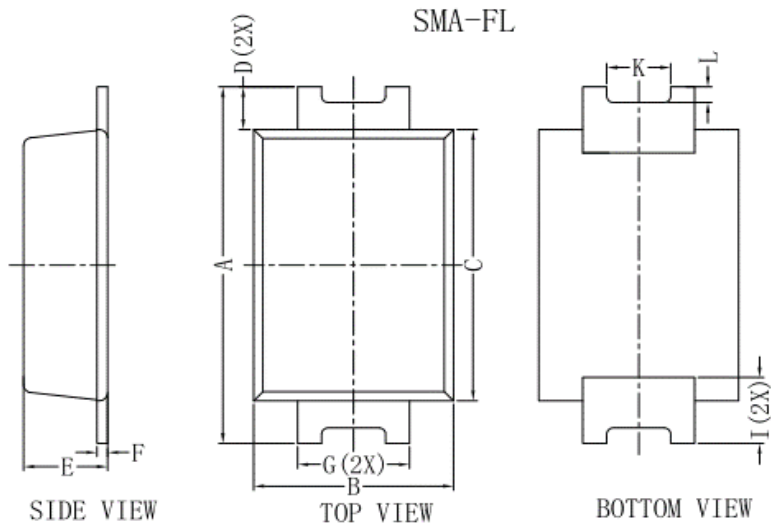


Fig 6. - Typical Junction Capacitance



3. OUTLINE AND DIMENSIONS



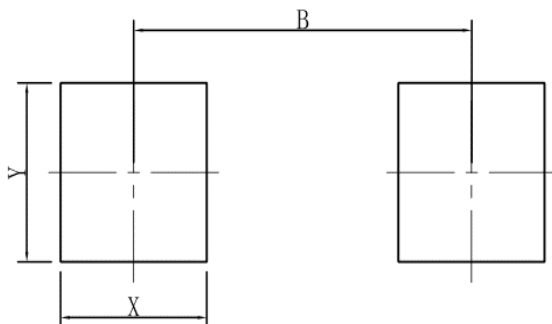
SMA-FL			
DIM	MIN	MAX	Typ.
A	4.40	4.80	4.60
B	2.30	2.70	2.60
C	3.30	3.70	3.50
D			0.55
E	0.90	1.20	1.05
F	0.11	0.21	0.17
G	1.30	1.50	1.40
I	-	-	0.90
K	-	-	0.80
L	-	-	0.20

All Dimensions in mm

GENERAL NOTES

1. Top package surface finish $Ra0.4 \pm 0.2 \mu m$
2. Bottom package surface finish $Ra0.7 \pm 0.2 \mu m$

4. SOLDERING FOOTPRINT



SMA-FL	
DIM	(mm)
X	1.60
Y	1.80
B	3.70



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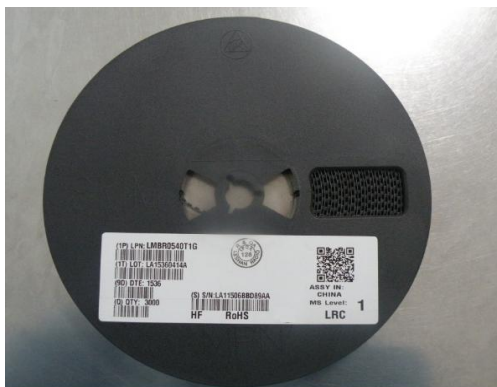
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8.1.2 Label position and QA stamp position.(Empty area) 标签张贴位置及QA印章位置。(印章盖在标签空白区)



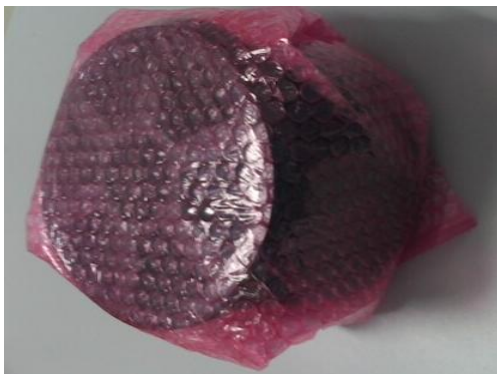
7英寸卷盘标签张贴及QA印章位置



13英寸卷盘标签张贴及QA印章位置

8.1.3 Ensure direction In the same reel. The same steel coil plate direction, With antistatic bubble to package reel. Refer to the below picture.

同一箱内的卷盘方向一致,用防静电泡沫对卷盘进行包裹。



7英寸卷盘防静电泡沫包裹



13英寸卷盘防静电泡沫包裹

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8.1.4 Put in the antistatic packing box after packaged reels. And QA stamp on the box label .

将包装好的卷盘放入防静电纸箱中，并在盒标签上盖章。



7 英寸卷盘内盒及标签



13 英寸卷盘内盒及标签

8.1.5 Product use printing inner box. 产品使用LRC印字内箱。



7英寸卷盘内箱印字（侧面）



13英寸卷盘内箱印字（正面）

8.1.6 Inner box packing quantity requirement. 内盒包装数量要求。

Product Description	QTY
SOD123-FL	1-10Reels
SOD323-HE	1-10Reels
SMA-FL	1-7Reels
SMB-FL	1-4Reels

8.1.7 With transparent tape sealing. 透明胶带封箱。

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7英寸内箱封盒



13英寸内箱封盒

8.1.8 Outer box size and packing quantity requirement, 外箱尺寸及包装数量要求。

Product Description	卷盘尺寸	Height (H)	Width (W)	Length (L)	Max. Qty
Power Device	7 英寸	410mm	400mm	445mm	12
Power Device	13 英寸	410mm	400mm	445mm	5



7 英寸卷盘产品装箱



13 英寸卷盘产品装箱

统一方向

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8.2 Standard Products Taping Specification

标准产品编带规范

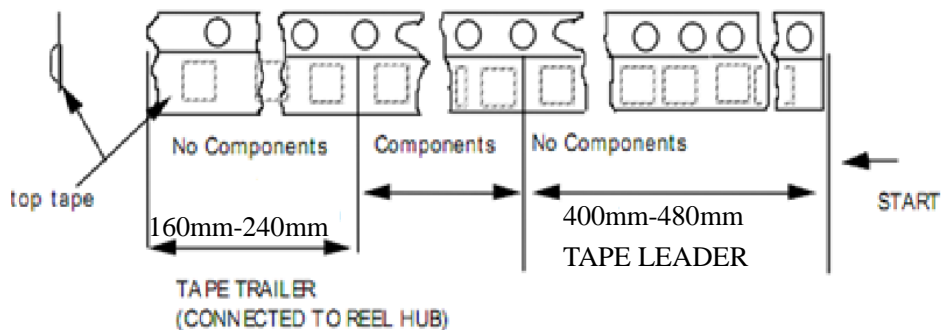
8.2.1 Tape length of no component

空带长度说明

Taping leader length 引导部分: $440\text{mm} \pm 40\text{mm}$, Tape trailer 尾部: $200\text{mm} \pm 40\text{mm}$

Figure 4

Tape Ends For Finished Goods Reel



8.2.2 Component packaging orientation: The cathode lead is close to the carrier tape's index hole.

产品放置方向: 印阴极带引脚邻近载带索引孔



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8.2.3 Tape enwind orientation

编带缠绕方向要求



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